



Comtech Telecommunications Corp. to Participate in Landenburg Thalmann 2019 Technology Expo

May 17, 2019

MELVILLE, N.Y.--(BUSINESS WIRE)--May 17, 2019-- May 17, 2019-- Comtech Telecommunications Corp. (NASDAQ:CMTL) announced today that it will participate in the Landenburg Thalmann 2019 Technology Expo on May 30, 2019 at the Convene meeting center in New York, NY.

Michael D. Porcelain, Senior Vice President and Chief Operating Officer, and Michael A. Bondi, Chief Financial Officer, will be available to provide an update on the company and its current business opportunities. The company will also conduct one-on-one meetings with investors throughout the day. To register for the conference and for one-on-one meetings, please contact your Landenburg Thalmann representative or visit <https://www.webcaster4.com/Webcast/Page/2068/30696>.

Comtech Telecommunications Corp. designs, develops, produces and markets innovative products, systems and services for advanced communications solutions. The Company sells products to a diverse customer base in the global commercial and government communications markets.

Certain information in this press release contains statements that are forward-looking in nature and involve certain significant risks and uncertainties. Actual results could differ materially from such forward-looking information. The Company's Securities and Exchange Commission filings identify many such risks and uncertainties. Any forward-looking information in this press release is qualified in its entirety by the risks and uncertainties described in such Securities and Exchange Commission filings.

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